S102S01/S102S02 S202S01/S202S02

SIP Type SSR for Medium **Power Control**

■ Features

- 1. High radiation resin mold package
- 2. RMS ON-state current

 $I_T: 8 \text{ Arms at } T_C \leq 80^{\circ}\text{C}$ (With heat sink)

- 3. Built-in zero-cross circuit (S102S02/S202S02)
- 4. High repetitive peak OFF-state voltage

S102S01/S102S02 **V**_{DRM}: MIN. 400V S202S01/S202S02 **V**_{DRM}: MIN. 600V

5. Isolation voltage between input and output

 $(V_{iso}: 4000V_{rms})$

6. Approved by CSA, No. LR63705 Recognized by UL, file No. E94758

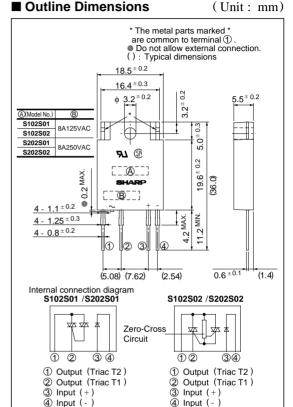
■ Applications

- 1. Automatic vending machines, programmable controllers
- 2. Amusement equipment

■ Model Line-ups

	For 100V lines	For 200V lines
For phase control No built-in zero-cross circuit	S102S01	S202S01
Built-in zero-cross circuit	S102S02	S202S02

■ Outline Dimensions



■ Absolute Maximum Ratings

Parameter		Carrala al	Rating		TT 1.	
		Symbol	S102S01 S102S02	S202S01 S202S02	Unit	
Input	Forward current	I_F	50		mA	_
	Reverse voltage	V _R	6		V	
Output	*1RMS ON-state current	I _T 8		3	A rms	
	*2Peak one cycle surge current	I surge	80		A	Ī
	Repetitive peak OFF-state voltage	V _{DRM}	400	600	V	_
	Non-repetitive peak OFF-state voltage	V _{DSM}	400	600	V	_
	Critical rate of rise of ON-state current	dI/dt	50		A/μ s	
	Operating frequency	f	45 to 65		Hz	
*3 Isolation voltage		V_{iso}	4 000		V _{rms}	
Operating temperature		T opr	- 25 to + 100		°C	
Storage temperature		T stg	- 30 to + 125		°C	_
*4Soldering temperature		T sol	26	50	°C	_

 $(Ta = 25^{\circ}C)$

 $*1 T_C \le 80^{\circ}C$

*2 50Hz sine wave, $T_j = 25^{\circ}C$

*3 60Hz AC for 1 minute, 40 to 60% RH, Apply voltages between input and output, by the dielectric withstand voltage tester with zerocross circuit.

(Input and output shall be shorted respectively).

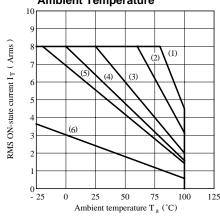
(Note) When the isolation voltage is necessary at using external heat sink, please use the insulation sheet. *4 For 10 seconds

■ Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage		VF	$I_F = 20 mA$	-	1.2	1.4	V
	Reverse current		I_R	$V_R = 3V$	-	-	10-4	A
Output	Repetitive peak OFF-sta	ite current	I_{DRM}	$V_D = V_{DRM}$	-	-	10-4	A
	ON-state voltage		V _T	Resistance load I _F = 20mA, I _T = 2Arms	-	-	1.5	V _{rms}
	Holding current		I_{H}	-	-	-	50	mA
	Critical rate of rise of OFF-stat	e voltage	dV/dt	$V_D = 2/3 \bullet V_{DRM}$	30	-	-	$V/\mu s$
	Critical rate of rise of co OFF-state voltage	Critical rate of rise of commutating OFF-state voltage		$T_j = 125^{\circ}C$, $dI_T/dt = -4.0A/ms$, $V_D = 400V$	5	-	-	V/μ s
	Zero-cross voltage	\$102\$02 \$202\$02	Vox	$I_F = 8mA$	-	-	35	V
Transfer charac- teristics	Minimum	S102S01 S202S01	_	$V_D = 12V$, $R_L = 30\Omega$	-	-	8	mA
	trigger S102S02 current S202S02	I_{FT}	$V_D = 6V$, $R_L = 30\Omega$	-	-	8	mA	
	Isolation resistance		R _{ISO}	DC500V, 40 to 60 % RH	1010	-	-	Ω
	Turn-on S102S01 S202S01 time S102S02 t	t on	AC 50Hz	-	-	1	ms	
				-	-	10	ms	
	Turn-off time		t off	-	-	-	10	ms
Thermal resistance (Between junction and case)		R th(j - c)	-	-	4.5	-	°C/W	
Thermal resi	Thermal resistance (Between junction and ambience)		R _{th(j-a)}	-	-	40	-	°C/W

Fig. 1 RMS ON-state Current vs.
Ambient Temperature



- (1) With infinite heat sink
- (2) With heat sink (200 x 200 x 2 mm Al plate)
- (3) With heat sink (100 x 100 x 2 mm Al plate)
- (4) With heat sink (75 x 75 x 2 mm Al plate)
- (5) With heat sink (50 x 50 x 2 mm Al plate)
- (6) Without heat sink

carried out.

(Note) With the Al heat sink set up vertically, tighten the device at the center of the Al heat sink with a torque of 0.4N • m and apply thermal conductive silicone grease on the heat sink mounting plate. Forcible cooling shall not be

Fig. 2 RMS ON-state Current vs. Case Temperature

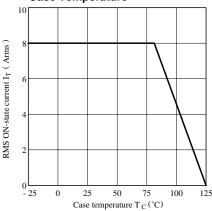


Fig. 4 Forward Current vs. Forward Voltage

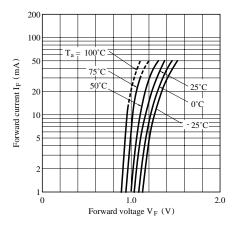


Fig. 6 Maximum ON-state Power Dissipation vs. RMS ON-state Current (Typical Value)

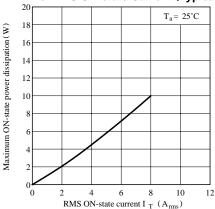


Fig. 3 Forward Current vs.

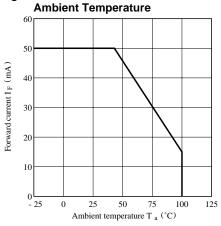


Fig. 5 Surge Current vs. Power-on Cycle

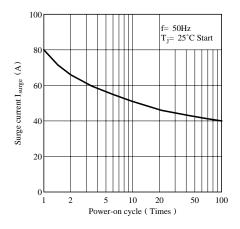


Fig. 7 Minimum Trigger Current vs.

Ambient Temperature (Typical Value)

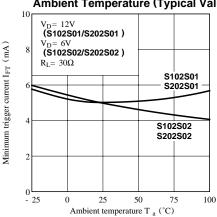
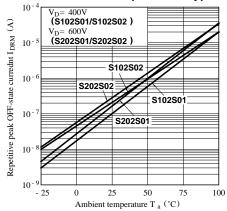


Fig. 8 Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value)



• Please refer to the chapter "Precautions for Use"

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